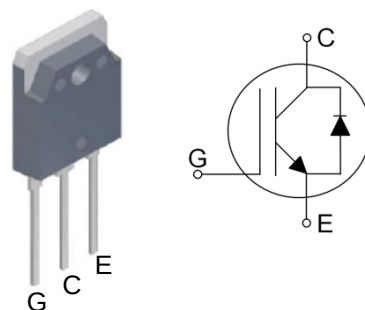


Features

- 600V Field Stop Trench IGBT Technology
- Low Conduction Loss
- Positive Temperature Coefficient
- Easy Parallel Operation
- RoHS Compliant
- JEDEC Qualification

Applications

UPS, Welder, Motor Inverter



Device	Package	Marking	Remark
TGAN40N60F2DS	TO-3PN	TGAN40N60F2DS	RoHS

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CES}	600	V
Gate-Emitter Voltage	V_{GES}	± 20	V
Continuous Collector Current	$T_C = 25^\circ\text{C}$	80	A
	$T_C = 100^\circ\text{C}$	40	A
Pulsed Collector Current (Note 1)	I_{CM}	120	A
Diode Continuous Forward Current	$T_C = 100^\circ\text{C}$	40	A
Diode Pulsed Forward Current (Note 2)	I_{FM}	200	A
Power Dissipation	$T_C = 25^\circ\text{C}$	236	W
	$T_C = 100^\circ\text{C}$	94	W
Operating Junction Temperature	T_{vj}	$-55 \sim 150$	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	$-55 \sim 150$	$^\circ\text{C}$
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	300	$^\circ\text{C}$

Notes :

- (1) Repetitive rating : Pulse width limited by maximum junction temperature, During production, high current switching capability is 100% verified with the inductive load single-pulse switching test. ($I_C=120A$)
- (2) Repetitive rating : Pulse width limited by maximum junction temperature.

Thermal Characteristics

Parameter	Symbol	Value	Unit
Maximum Thermal resistance, Junction-to-Case	$R_{\theta JC}$ (IGBT)	0.53	$^\circ\text{C/W}$
Maximum Thermal resistance, Junction-to-Case	$R_{\theta JC}$ (DIODE)	1.43	$^\circ\text{C/W}$
Maximum Thermal resistance, Junction-to-Ambient	$R_{\theta JA}$	40	$^\circ\text{C/W}$

Electrical Characteristics of the IGBT $T_{vj}=25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
OFF						
Collector – Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0V, I _C = 1mA	600	--	--	V
Zero Gate Voltage Collector Current	I _{CES}	V _{CE} = 600V, V _{GE} = 0V	--	--	1	mA
Gate – Emitter Leakage Current	I _{GES}	V _{CE} = 0V, V _{GE} = ± 20V	--	--	± 250	nA
Integrated Gate Resistance	R _{G(int)}	f = 1MHz, Open Collector	--	2.0	--	Ω
ON						
Gate – Emitter Threshold Voltage	V _{GE(TH)}	V _{GE} = V _{CE} , I _C = 40mA	4.5	6.0	7.5	V
Collector – Emitter Saturation Voltage	V _{CE(SAT)}	V _{GE} = 15V, I _C = 40A, T _{vj} = 25 °C	--	2.0	2.4	V
		V _{GE} = 15V, I _C = 40A, T _{vj} = 150 °C	--	2.3	--	V
DYNAMIC						
Input Capacitance	C _{IES}	V _{CE} = 30V V _{GE} = 0V f = 1MHz	--	2650	--	pF
Output Capacitance	C _{OES}		--	135	--	pF
Reverse Transfer Capacitance	C _{RES}		--	75	--	pF
Total Gate Charge	Q _g	V _{CC} = 400V, I _C = 40A V _{GE} = 15V	--	115	172	nC
Gate-Emitter Charge	Q _{ge}		--	17	25	nC
Gate-Collector Charge	Q _{gc}		--	60	90	nC
SWITCHING (Note 3)						
Turn-On Delay Time	t _{d(on)}	V _{CC} = 400V, I _C = 20A R _G = 5Ω, V _{GE} = 15V Inductive Load, T _{vj} = 25 °C	--	24	--	ns
Rise Time	t _r		--	17	--	ns
Turn-Off Delay Time	t _{d(off)}		--	84	--	ns
Fall Time	t _f		--	18	--	ns
Turn-On Switching Loss	E _{ON}		--	0.46	--	mJ
Turn-Off Switching Loss	E _{OFF}		--	0.05	--	mJ
Total Switching Loss	E _{TS}		--	0.51	--	mJ
Turn-On Delay Time	t _{d(on)}	V _{CC} = 400V, I _C = 40A R _G = 5Ω, V _{GE} = 15V Inductive Load, T _{vj} = 25 °C	--	30	--	ns
Rise Time	t _r		--	46	--	ns
Turn-Off Delay Time	t _{d(off)}		--	79	--	ns
Fall Time	t _f		--	19	--	ns
Turn-On Switching Loss	E _{ON}		--	1.21	1.82	mJ
Turn-Off Switching Loss	E _{OFF}		--	0.14	0.21	mJ
Total Switching Loss	E _{TS}		--	1.35	2.03	mJ

Electrical Characteristics of the IGBT $T_{vj}=25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
SWITCHING (Note 3)						
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400\text{V}, I_C = 20\text{A}$ $R_G = 5\Omega, V_{GE} = 15\text{V}$ Inductive Load, $T_{vj} = 150^{\circ}\text{C}$	--	25	--	ns
Rise Time	t_r		--	18	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	113	--	ns
Fall Time	t_f		--	28	--	ns
Turn-On Switching Loss	E_{ON}		--	0.77	--	mJ
Turn-Off Switching Loss	E_{OFF}		--	0.20	--	mJ
Total Switching Loss	E_{TS}		--	0.97	--	mJ
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400\text{V}, I_C = 40\text{A}$ $R_G = 5\Omega, V_{GE} = 15\text{V}$ Inductive Load, $T_{vj} = 150^{\circ}\text{C}$	--	29	--	ns
Rise Time	t_r		--	47	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	98	--	ns
Fall Time	t_f		--	30	--	ns
Turn-On Switching Loss	E_{ON}		--	1.73	2.60	mJ
Turn-Off Switching Loss	E_{OFF}		--	0.38	0.57	mJ
Total Switching Loss	E_{TS}		--	2.11	3.17	mJ

Notes :

(3) Not subject to production test – verified by design/characterization

Electrical Characteristics of the DIODE $T_{vj}=25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
Diode Forward Voltage	V_{FM}	$I_F = 20\text{A}, T_{vj} = 25^{\circ}\text{C}$	--	1.70	--	V
		$I_F = 20\text{A}, T_{vj} = 150^{\circ}\text{C}$	--	1.46	--	V
		$I_F = 40\text{A}, T_{vj} = 25^{\circ}\text{C}$	--	2.10	--	V
		$I_F = 40\text{A}, T_{vj} = 150^{\circ}\text{C}$	--	1.95	--	V
Reverse Recovery Time	t_{rr}	$I_F = 20\text{A},$ $di/dt = 200\text{A}/\mu\text{s},$ $T_{vj} = 25^{\circ}\text{C}$	--	58	--	ns
Reverse Recovery Current	I_{rr}		--	5.0	--	A
Reverse Recovery Charge	Q_{rr}		--	168	--	nC
Reverse Recovery Time	t_{rr}	$I_F = 20\text{A},$ $di/dt = 200\text{A}/\mu\text{s},$ $T_{vj} = 150^{\circ}\text{C}$	--	155	--	ns
Reverse Recovery Current	I_{rr}		--	10.2	--	A
Reverse Recovery Charge	Q_{rr}		--	950	--	nC
Reverse Recovery Time	t_{rr}	$I_F = 40\text{A},$ $di/dt = 200\text{A}/\mu\text{s},$ $T_{vj} = 25^{\circ}\text{C}$	--	60	--	ns
Reverse Recovery Current	I_{rr}		--	5.7	--	A
Reverse Recovery Charge	Q_{rr}		--	196	--	nC
Reverse Recovery Time	t_{rr}	$I_F = 40\text{A},$ $di/dt = 200\text{A}/\mu\text{s},$ $T_{vj} = 150^{\circ}\text{C}$	--	158	--	ns
Reverse Recovery Current	I_{rr}		--	10.8	--	A
Reverse Recovery Charge	Q_{rr}		--	1120	--	nC

IGBT Characteristics

Fig. 1 IGBT Output Characteristics

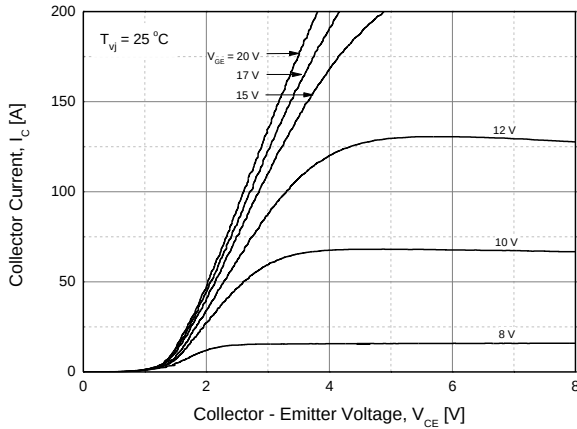


Fig. 2 IGBT Output Characteristics

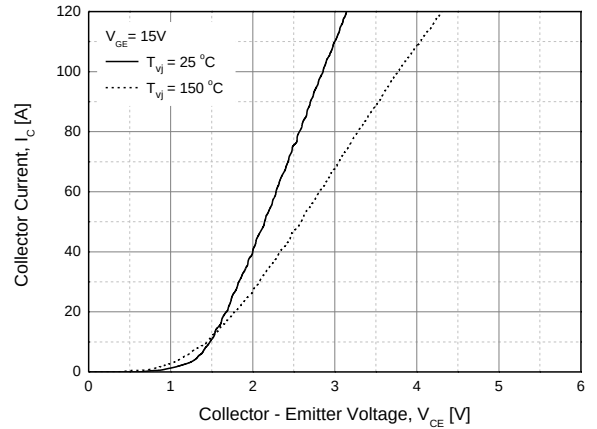


Fig. 3 IGBT Saturation Voltage vs. Junction Temperature

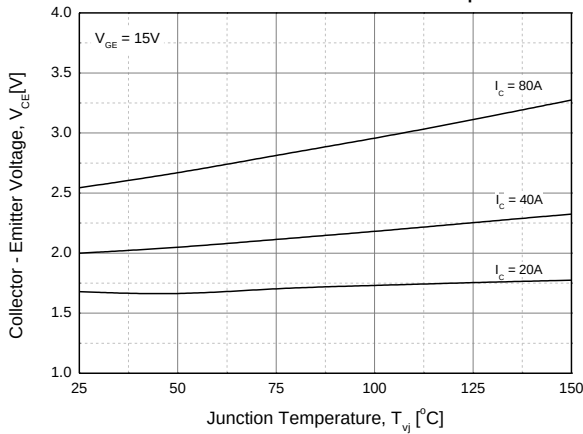


Fig. 4 IGBT Saturation Voltage vs. Gate Bias

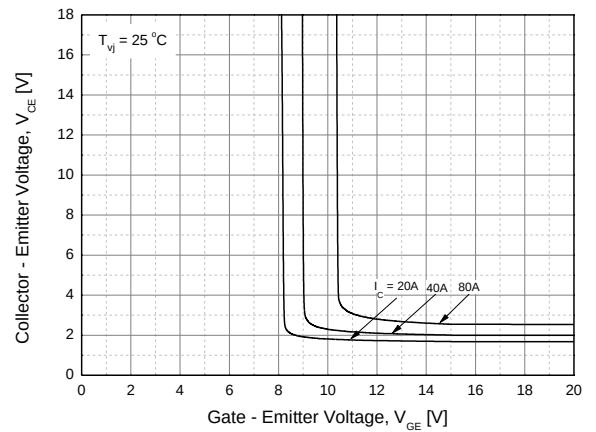


Fig. 5 IGBT Saturation Voltage vs. Gate Bias

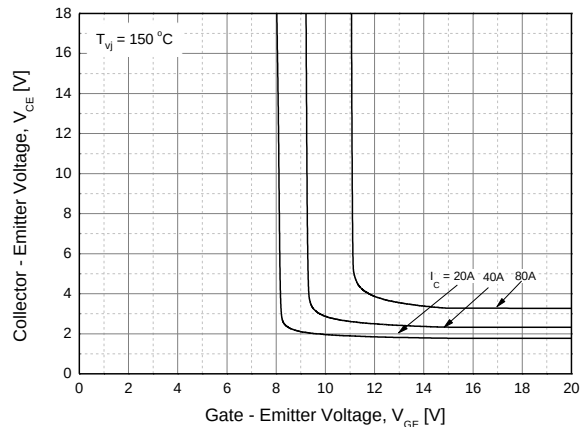
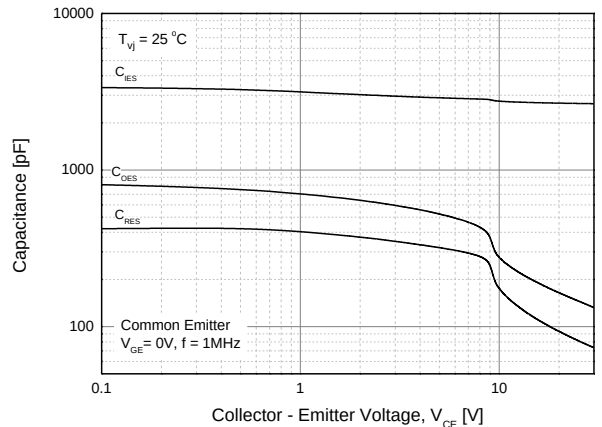


Fig. 6 IGBT Capacitance Characteristics



IGBT Characteristics

Fig. 7 Turn-on Time vs. Gate Resistor

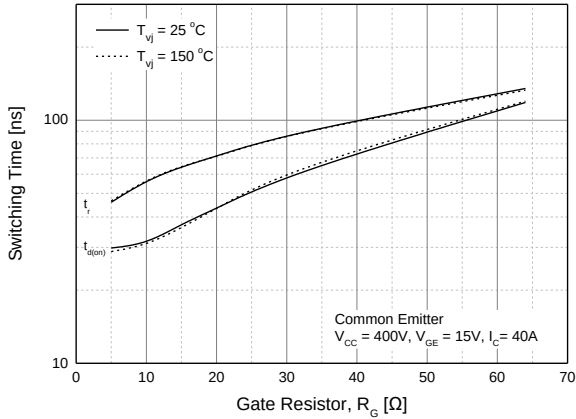


Fig. 8 Turn-off Time vs. Gate Resistor

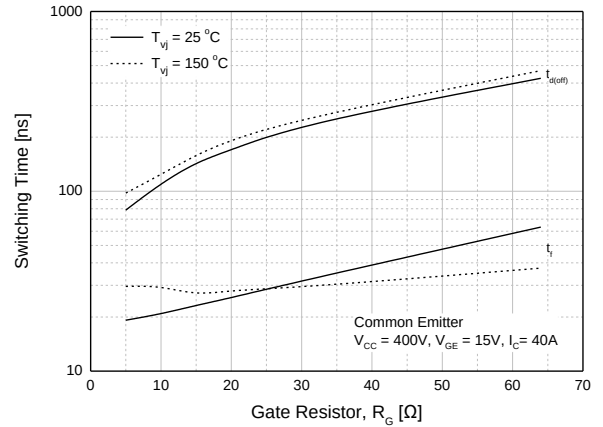


Fig. 9 Switching Loss vs. Gate Resistor

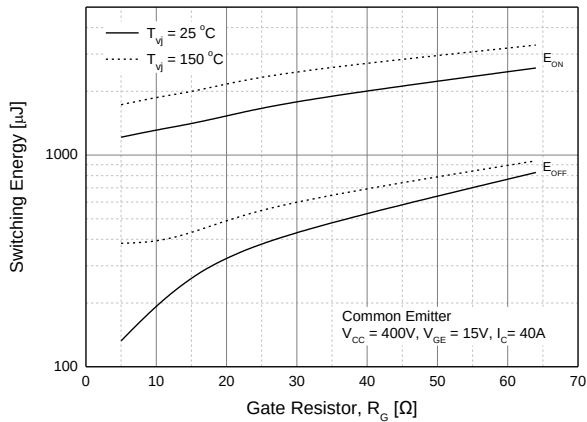


Fig. 10 Turn-on Time vs. Collector Current

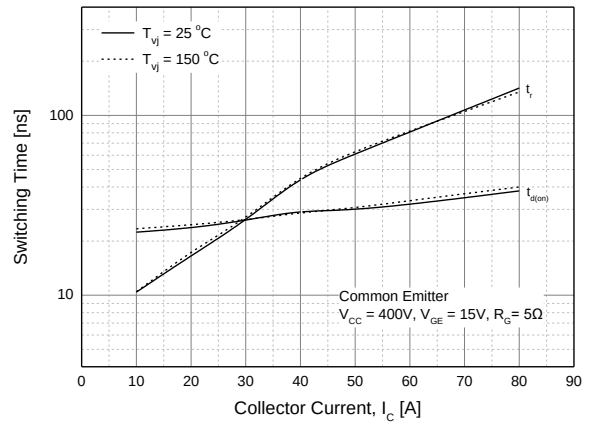


Fig. 11 Turn-off Time vs. Collector Current

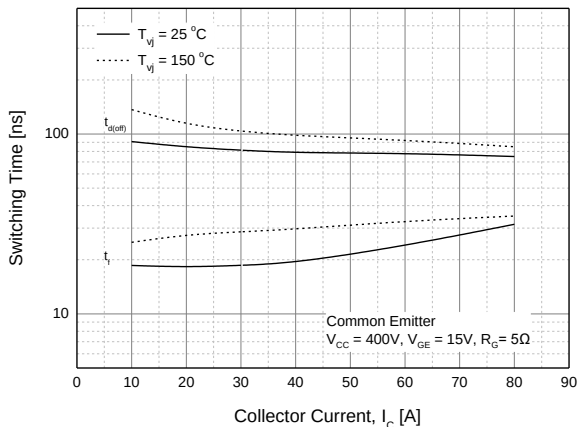
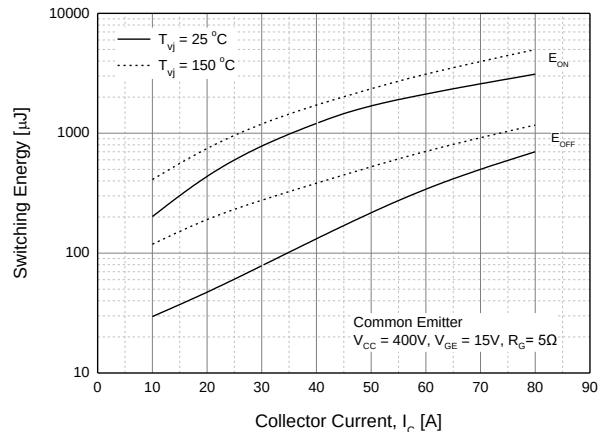


Fig. 12 Switching Loss vs. Collector Current



IGBT Characteristics

Fig. 13 Gate Charge Characteristics

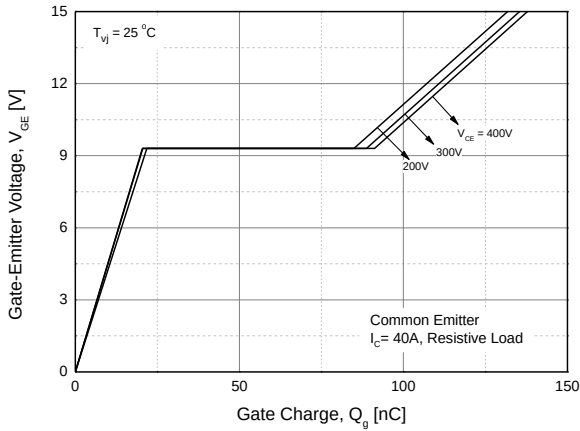


Fig. 14 SOA

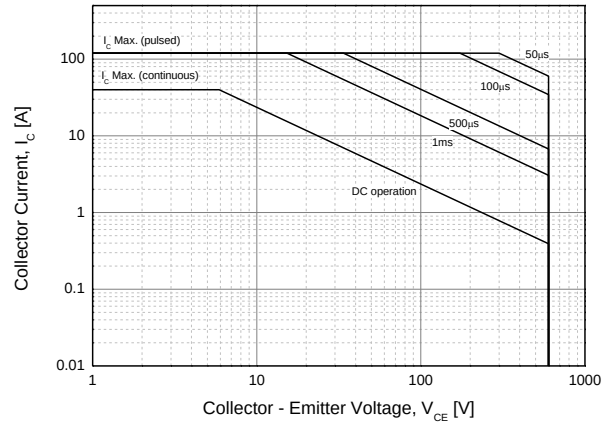


Fig. 15 RBSOA

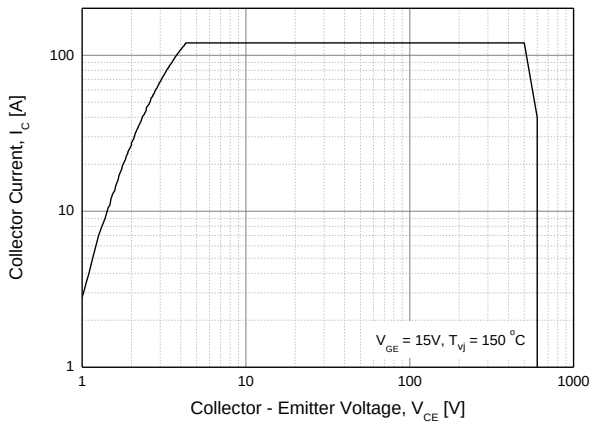


Fig. 16 Transient Thermal Impedance of IGBT

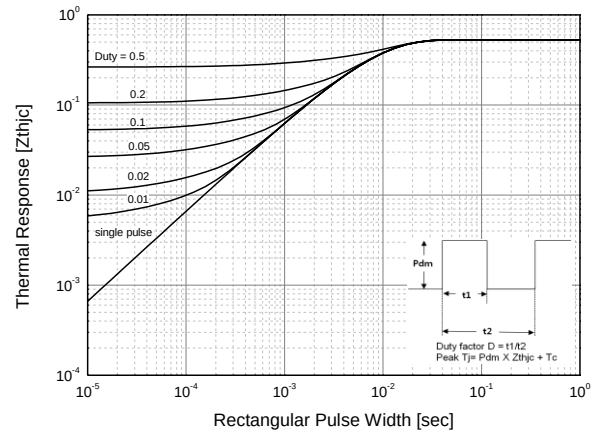
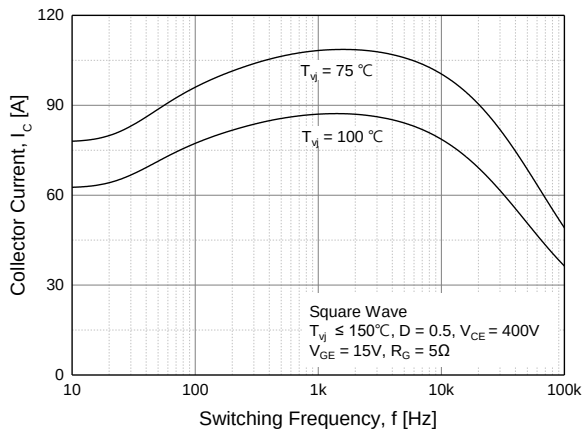


Fig. 17 Load Current vs. Frequency



Diode Characteristics

Fig. 18 Diode Conduction Characteristics

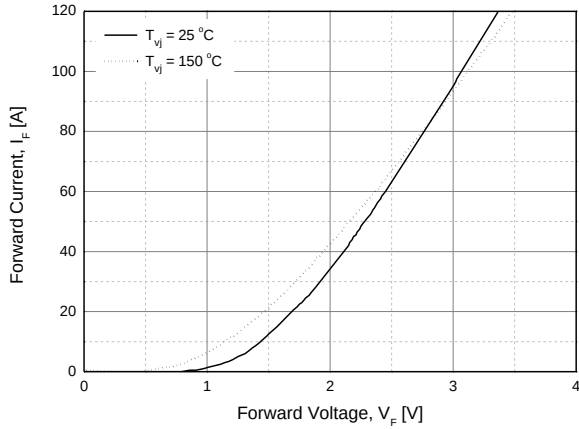


Fig. 19 Reverse Recovery Current vs. Forward Current

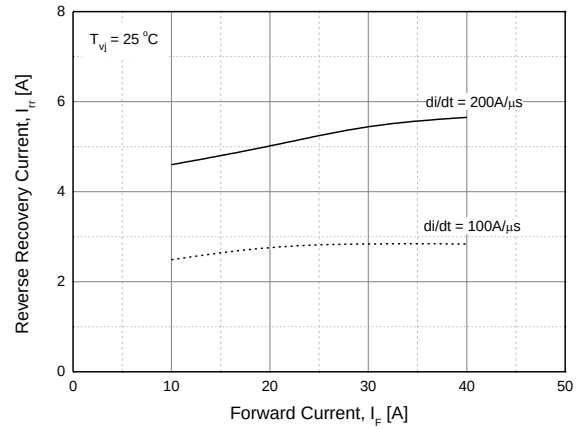


Fig. 20 Reverse Recovery Charge vs. Forward Current

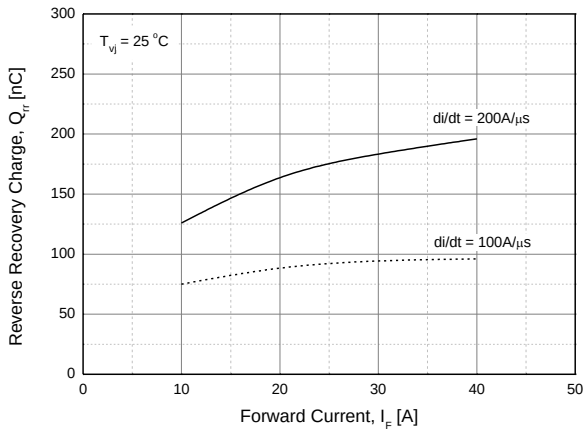
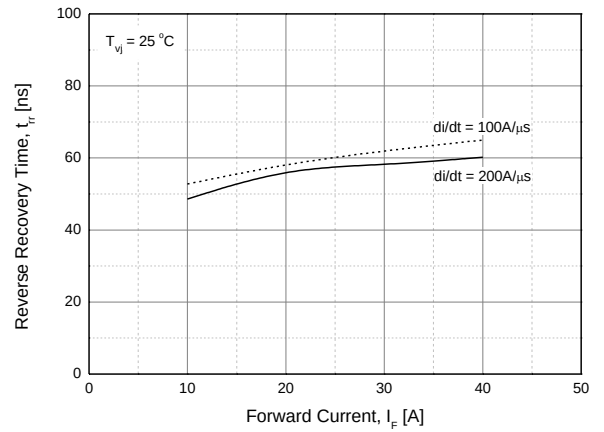
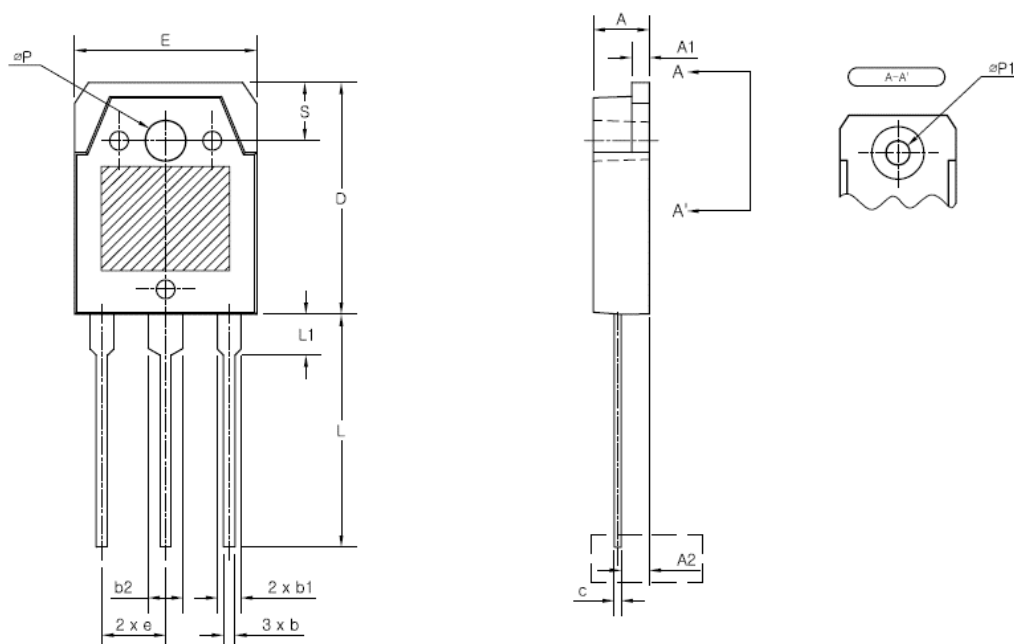


Fig. 21 Reverse Recovery Time vs. Forward Current



TO-3PN MECHANICAL DATA



SYMBOL	mm		
	MIN	NOM	MAX
A	4.6	4.8	5
A1	1.45	1.5	1.65
A2	2.2	2.4	2.6
b	0.8	1	1.2
b1	2.8	3	3.2
b2	1.8	2	2.2
c	0.55	0.6	0.75
D	19.20	19.65	20.10
E	15.4	15.6	15.8
e	5.15	5.45	5.75
L	19.8	20	20.2
L1	3.3	3.5	3.7
ΦP	3.5		
ΦP1	3.2		
S	5		

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